



## Product Change Notification / JAON-04TMOL584

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### Date:

09-Feb-2021

### Product Category:

8-bit Microcontrollers, Analog to Digital Converters, Capacitive Touch Sensors, Charge Pump DC-to-DC Converters, Digital Potentiometers, Digital to Analog Converters, Instrumentation Amplifier, Interface-Controller Area Network (CAN), Interface- Infrared Products, Interface- LIN Transceiver, KEELOQ® Encoder Devices, Linear Comparators, Linear Op Amps, Linear Programmable Gain Amplifiers, Linear Selectable Gain Amplifiers, Memory, Piezoelectric Horn Drivers and CO Detector, Power Management - System Supervisors/Voltage Detectors, Power MOSFET Drivers, Real-Time Clock/Calendar, RFID tag ICs - microID® ICs, Temperature Sensors

### PCN Type:

Manufacturing Change

### Notification Subject:

CCB 4539 Initial Notice: Qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper wire with gold flash (CuPdAu) bond wire material assembled at MMT assembly site.

### Affected CPNs:

[JAON-04TMOL584\\_Affected\\_CPN\\_02092021.pdf](#)

[JAON-04TMOL584\\_Affected\\_CPN\\_02092021.csv](#)

### Notification Text:

**PCN Status:** Initial notification

**PCN Type:** Manufacturing Change

**Microchip Parts Affected:** Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:** Qualification of a new lead frame design for selected products available in 8L SOIC package using

8390A die attach and palladium coated copper wire with gold flash (CuPdAu) bond wire material assembled at MMT assembly site.

**Pre Change:**

Using lead frame without lead lock

**Post Change:**

Using lead frame with lead lock

**Pre and Post Change Summary:**

	<b>Pre Change</b>	<b>Post Change</b>
<b>Assembly Site</b>	Microchip Technology Thailand (Branch) / MMT	Microchip Technology Thailand (Branch) / MMT
<b>Wire material</b>	CuPdAu	CuPdAu
<b>Die attach material</b>	8390A	8390A
<b>Molding compound material</b>	G600V	G600V
<b>Lead frame material</b>	CDA194	CDA194
<b>Lead Frame Lead Lock</b>	No	Yes
	See attached pre and post change comparison	

**Impacts to Data Sheet:** None

**Change Impact:**None

**Reason for Change:**To improve productivity by qualifying new lead frame design.

**Change Implementation Status:**In Progress

**Estimated Qualification Completion Date:**March 2021

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

**Time Table Summary:**

Workweek	February 2021				March 2021				
	06	07	08	09	10	11	12	13	14
Initial PCN Issue Date		X							
Qual Report Availability							X		
Final PCN Issue Date							X		

**Method to Identify Change:** Traceability code

**Qualification Plan:** Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Plan.

**Revision History:** February 9, 2021: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

## **Attachments:**

[PCN\\_JAON-04TMOL584\\_Qual\\_Plan.pdf](#)

[PCN\\_JAON-04TMOL584\\_Pre and Post Change\\_Summary.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

## **Terms and Conditions:**

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN)

MCP14E6-E/SN  
MCP14E6T-E/SN  
MCP14E7-E/SN  
MCP14E7T-E/SN  
MCP14E8-E/SN  
MCP14E8T-E/SN  
MCP14E9-E/SN  
MCP14E9T-E/SN  
MCP14E10-E/SN  
MCP14E10T-E/SN  
MCP14E11-E/SN  
MCP14E11T-E/SN  
25LC040/SN  
25C040/SN  
25C040-E/SN  
25LC040-I/SN  
25AA040-I/SN  
25C040-I/SN  
25LC040T/SN  
25C040T/SN  
25LC040T-I/SN  
25AA040T-I/SN  
25C040T-I/SN  
25C040T-E/SN  
93LC46BT-I/SNRVA  
93C66B-I/SN  
93C66BT-I/SN  
24C00/SN  
24C00-E/SN  
24C00-I/SN  
24C00T/SN  
24C00T-I/SN  
24C00T-E/SN  
24LC00/SN  
24AA00/SN  
24LC00-I/SN  
24AA00-I/SN  
24LC00T/SN  
24AA00T/SN  
24LC00T-I/SN  
24AA00T-I/SN  
93LC46/SN  
93LC46X/SN  
93LC46B/SN  
93LC46BX/SN  
93LC46-I/SN

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JAON-04TMOL584 - CCB 4539 Initial Notice: Qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper wire with gold flash (CuPdAu) bond wire material assembled at MMT assembly site.

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93LC46X-I/SN

93LC46B-I/SN

93LC46BX-I/SN

93AA46-I/SN

93AA46/SN

93LC46T/SN

93LC46XT/SN

93LC46BT/SN

93LC46BXT/SN

93AA46T/SN

93LC46T-I/SN

93LC46XT-I/SN

93LC46BT-I/SN

93LC46BXT-I/SN

93AA46T-I/SN

93LC56/SN

93LC56X/SN

93LC66/SN

93LC66X/SN

93AA66/SN

93AA66X/SN

93C56-E/SN

93C66-E/SN

93LC56-I/SN

93LC66-I/SN

93LC66X-I/SN

93AA56-I/SN

93AA66-I/SN

93AA56/SN

93LC56T/SN

93LC66T/SN

93AA56T/SN

93AA66T/SN

93AA66XT/SN

93LC56T-I/SN

93LC66T-I/SN

93LC66XT-I/SN

93AA56T-I/SN

93AA66T-I/SN

93C56T-E/SN

93C66T-E/SN

25LC080/SN

25AA080/SN

25C080/SN

25C080-E/SN

25LC080-I/SN

25AA080-I/SN

25C080-I/SN

25LC080T/SN

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25AA080T/SN

25C080T/SN

25LC080T-I/SN

25AA080T-I/SN

25C080T-I/SN

25C080T-E/SN

25LC160/SN

25AA160/SN

25C160/SN

25C160-E/SN

25LC160-I/SN

25AA160-I/SN

25C160-I/SN

25LC160T/SN

25AA160T/SN

25C160T/SN

25LC160T-I/SN

25AA160T-I/SN

25C160T-I/SN

25C160T-E/SN

93LC76/SN

93AA76/SN

93C76-E/SN

93LC76-I/SN

93LC76T/SN

93AA76T/SN

93LC76T-I/SN

93C76T-E/SN

93LC86/SN

93AA86/SN

93C86-E/SN

93LC86-I/SN

93LC86T/SN

93AA86T/SN

93LC86T-I/SN

93C86T-E/SN

HCS300/SN042

HCS300/SN

HCS300-I/SN

HCS300T/SN031

HCS300T/SN

HCS300T-I/SN029

HCS300T-I/SN047

HCS300T-I/SN049

HCS300T-I/SN053

HCS300T-I/SN

HCS301/SN024

HCS301/SN

HCS301-I/SN

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HCS301T/SN022

HCS301T/SN024

HCS301T/SN

HCS301T-I/SN028

HCS301T-I/SN029

HCS301T-I/SN

HCS200/SN

HCS200-I/SN

HCS200T/SN

HCS200T-I/SN

24LCS21A/SN

24LC21A/SN

24LC21/SN

24LC21A-I/SN100

24LCS21A-I/SN

24LC21A-I/SN

24LC21-I/SN

24LCS21AT/SN

24LC21AT/SN

24LC21T/SN

24LC21AT-I/SN100

24LCS21AT-I/SN

24LC21AT-I/SN

24LC21T-I/SN

24LCS22A-I/SN

24LC22A-I/SN

24LCS22AT-I/SN

24LC22AT-I/SN

MCP606-I/SN

MCP608-I/SN

MCP606T-I/SN

MCP608T-I/SN

PIC12C508A-04/SN208

PIC12LC508A-04/SN

PIC12C508A-04/SN

PIC12C508A-04E/SN

PIC12LC508A-04I/SN

PIC12C508A-04I/SN

PIC12C508AT-04/SN208

PIC12C508AT-04/SN

PIC12C508AT-04I/SN077

PIC12C508AT-04I/SN123

PIC12LC508AT-04I/SN167

PIC12LC508AT-04I/SN168

PIC12C508AT-04I/SN221

PIC12C508AT-04I/SN231

PIC12C508AT-04I/SN

PIC12LC509A-04/SN

PIC12C509A-04/SN

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PIC12C509A-04E/SN

PIC12LC509A-04I/SN

PIC12C509A-04I/SN

PIC12C509A-04I/SNC09

PIC12C509AT-04/SN

PIC12LC509AT-04I/SNG063

PIC12LC509AT-04I/SN126

PIC12LC509AT-04I/SN

PIC12C509AT-04E/SN

MCP130-270I/SN

MCP130-300I/SN

MCP130-315I/SN

MCP130-450I/SN

MCP130-460I/SN

MCP130-475I/SN

MCP130-485I/SN

MCP130T-270I/SN

MCP130T-300I/SN

MCP130T-315I/SN

MCP130T-450I/SN

MCP130T-460I/SN

MCP130T-475I/SN

MCP130T-485I/SN

MCP120-270I/SN

MCP120-300I/SN

MCP120-315I/SN

MCP120-450I/SN

MCP120-460I/SN

MCP120-475I/SN

MCP120-485I/SN

MCP120T-270I/SN

MCP120T-300I/SN

MCP120T-315I/SN

MCP120T-450I/SN

MCP120T-460I/SN

MCP120T-475I/SN

MCP120T-485I/SN

MCP607-I/SN

MCP607T-I/SN

MCP607T-I/SNA21

MCP6021-E/SN

MCP6023-E/SN

MCP6021-I/SN

MCP6023-I/SN

MCP6021T-I/SN

MCP6023T-I/SN

MCP6021T-E/SN

MCP6023T-E/SN

MCP6022-E/SN



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MCP6022-I/SN  
MCP6022T-I/SN  
MCP6022T-E/SN  
MCP616-I/SN  
MCP618-I/SN  
MCP616T-I/SN  
MCP618T-I/SN  
MCP617-I/SN  
MCP617T-I/SN  
MCP6541-E/SN  
MCP6543-E/SN  
MCP6541-I/SN  
MCP6543-I/SN  
MCP6541T-I/SN  
MCP6543T-I/SN  
MCP6541T-E/SN  
MCP6543T-E/SN  
MCP6542-E/SN  
MCP6542-I/SN  
MCP6542T-I/SN  
MCP6542T-E/SN  
MCP6546-E/SN  
MCP6548-E/SN  
MCP6546-I/SN  
MCP6548-I/SN  
MCP6546T-I/SN  
MCP6548T-I/SN  
MCP6546T-E/SN  
MCP6548T-E/SN  
MCP6547-E/SN  
MCP6547-I/SN  
MCP6547T-I/SN  
MCP6547T-E/SN  
MCP6S21-I/SN  
MCP6S21T-I/SN  
MCP6S22-I/SN  
MCP6S22T-I/SN  
MCP6272-E/SN  
MCP6282-E/SN  
MCP6292-E/SN  
MCP6272T-E/SN  
MCP6282T-E/SN  
MCP6292T-E/SN  
MCP6L92T-E/SN  
MCP6275-E/SN  
MCP6285-E/SN  
MCP6295-E/SN  
MCP6275T-E/SN  
MCP6285T-E/SN

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MCP6295T-E/SN

MCP6L72T-E/SN

MCP6271-E/SN

MCP6273-E/SN

MCP6281-E/SN

MCP6283-E/SN

MCP6291-E/SN

MCP6293-E/SN

MCP6271T-E/SN

MCP6273T-E/SN

MCP6281T-E/SN

MCP6283T-E/SN

MCP6291T-E/SN

MCP6293T-E/SN

MCP6L71T-E/SN

MCP6L91T-E/SN

MCP6031-E/SN

MCP6033-E/SN

MCP6031T-E/SN

MCP6033T-E/SN

MCP6032-E/SN

MCP6032T-E/SN

MCP6032T-E/SNEIE

MCP6051-E/SN

MCP6061-E/SN

MCP6071-E/SN

MCP6051T-E/SN

MCP6061T-E/SN

MCP6071T-E/SN

MCP6052-E/SN

MCP6062-E/SN

MCP6072-E/SN

MCP6052T-E/SN

MCP6062T-E/SN

MCP6072T-E/SN

MCP41010-E/SN

MCP41010-I/SN

MCP41010T-I/SN

MCP41010T-E/SN

MCP601-E/SN

MCP603-E/SN

MCP601-I/SN

MCP603-I/SN

MCP601T-I/SN

MCP603T-I/SN

MCP601T-E/SN

MCP603T-E/SN

MCP6L1T-E/SN

MCP3201-BI/SN

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MCP3201-CI/SN

MCP3201T-BI/SN

MCP3201T-CI/SN

MCP3202-BI/SN

MCP3202-CI/SN

MCP3202T-BI/SN

MCP3202T-CI/SN

MCP3001-I/SN

MCP3001T-I/SN

MCP3002-I/SN

MCP3002T-I/SN

MCP602-E/SN

MCP602-I/SN

MCP602-I/SNREL

MCP602T-I/SN

MCP602T-E/SN

MCP6L2T-E/SN

MCP41050-E/SN

MCP41050-I/SN

MCP41050T-I/SN

MCP41050T-E/SN

MCP41100-E/SN

MCP41100-I/SN

MCP41100T-I/SN

MCP41100T-E/SN

MCP3301-BI/SN

MCP3301-CI/SN

MCP3301T-BI/SN

MCP3301T-CI/SN

MCP6042-E/SN

MCP6042-I/SN

MCP6042-I/SNREL

MCP6042T-I/SN

MCP6042T-E/SN

MCP6142-E/SN

MCP6142-I/SN

MCP6142T-I/SN

MCP6142T-E/SN

MCP6002-E/SN

MCP6002-I/SN

MCP6002T-I/SN

MCP6002T-E/SN

MCP6L02T-E/SN

MCP6231-E/SN

MCP6231T-E/SN

MCP6241-E/SN

MCP6241T-E/SN

MCP6232-E/SN

MCP6232T-E/SN

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MCP6242-E/SN

MCP6242T-E/SN

MCP6S91-E/SN

MCP6S91T-E/SN

MCP6S92-E/SN

MCP6S92T-E/SN

MCP6G01-E/SN

MCP6G01T-E/SN

MCP6G03-E/SN

MCP6G03T-E/SN

MCP6G02-E/SN

MCP6G02T-E/SN

MCP6041-E/SN

MCP6043-E/SN

MCP6041-I/SN

MCP6043-I/SN

MCP6041T-I/SN

MCP6043T-I/SN

MCP6041T-E/SN

MCP6043T-E/SN

MCP6141-E/SN

MCP6143-E/SN

MCP6141-I/SN

MCP6143-I/SN

MCP6141T-I/SN

MCP6143T-I/SN

MCP6141T-E/SN

MCP6143T-E/SN

MCP6402-E/SN

MCP6402-H/SN

MCP6407T-H/SN

MCP6407-H/SN

MCP6402T-H/SN

MCP6402T-E/SN

MCP6442-E/SN

MCP6442T-E/SN

24LC01B/SN

24LC01B-E/SN

24LC01B-I/SN

24LC01BT/SN

24LC01BT-I/SN

24LC01BT-I/SNA21

24LC01BT-I/SNA23

24LC01BT-I/SNRVE

24LC01BT-E/SN

24LC04B-I/SN

24LC04BT-I/SN

24LC04BT-I/SNA29

24LC64-I/SNRVA

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24LC64I-I/SNKVA

25LC640-E/SN

25LC640-I/SN

25AA640-I/SN

25LC640T-I/SN

25AA640T-I/SN

25LC640T-E/SN

25LC320/SN

25C320/SN

25LC320-E/SN

25C320-E/SN

25LC320-I/SN

25AA320-I/SN

25C320-I/SN

25LC320T/SN

25C320T/SN

25LC320T-I/SN

25AA320T-I/SN

25C320T-I/SN

25LC320T-E/SN

25C320T-E/SN

HCS201/SN

HCS201-I/SN036

HCS201-I/SN

HCS201T/SN017

HCS201T/SN021

HCS201T/SN024

HCS201T/SN

HCS201T-I/SN

HCS101-I/SN

24C02C/SN

24C02C-E/SN

24C02C-I/SN

24C02CT/SN

24C02CT-I/SN

24C02CT-E/SN

MCRF450X/SN

MCRF450TX/SN

PIC12F675-C/SN

PIC12F675-E/SN

PIC12F675-I/SN102

PIC12F675-I/SN112

PIC12F675-I/SN166

PIC12F675-I/SN172

PIC12F675-I/SN177

PIC12F675-I/SN202

PIC12F675-I/SN

PIC12F675-I/SNC15

PIC12F675T-C/SN

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PIC12F675T-I/SN026  
PIC12F675T-I/SN049  
PIC12F675T-I/SN075  
PIC12F675T-I/SN079  
PIC12F675T-I/SN085  
PIC12F675T-I/SN121  
PIC12F675T-I/SN131  
PIC12F675T-I/SN145  
PIC12F675T-I/SN150  
PIC12F675T-I/SN152  
PIC12F675T-I/SN153  
PIC12F675T-I/SN166  
PIC12F675T-I/SN172  
PIC12F675T-I/SN173  
PIC12F675T-I/SN178  
PIC12F675T-I/SN179  
PIC12F675T-I/SN185  
PIC12F675T-I/SN190  
PIC12F675T-I/SN191  
PIC12F675T-I/SN194  
PIC12F675T-I/SN195  
PIC12F675T-I/SN199  
PIC12F675T-I/SN200  
PIC12F675T-I/SN201  
PIC12F675T-I/SN202  
PIC12F675T-I/SN206  
PIC12F675T-I/SN207  
PIC12F675T-I/SN208  
PIC12F675T-I/SN  
PIC12F675T-I/SNC15  
PIC12F675T-E/SN073  
PIC12F675T-E/SN082  
PIC12F675T-E/SN091  
PIC12F675T-E/SN  
24LC256-E/SN  
24LC256-I/SN  
24LC256-I/SNRVE  
24AA256-I/SN  
24AA256-I/SNRVE  
24LC256-I/SNREL  
24LC256T-I/SN  
24LC256T-I/SNRVE  
24AA256T-I/SN  
24AA256T-I/SNRVE  
24LC256T-E/SN  
24LC256T-E/SNRVE  
24FC256-I/SN  
24FC256T-I/SN  
24LC128-E/SN

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24LC128-I/SN

24LC128-I/SNRVE

24AA128-I/SN

24LC128T-I/SN

24LC128T-I/SNRVE

24AA128T-I/SN

24LC128T-E/SN

24FC128-I/SN

24FC128-I/SNRVE

24FC128T-I/SN

24FC128T-I/SNRVE

24AA64/SN

24LC64-E/SN

24LC64-I/SN

24AA64-I/SN

24LC64-I/SNRVE

24AA64T/SN

24LC64T-I/SN

24LC64T-I/SNA22

24AA64T-I/SN

34A83GT-I/SN

24LC64T-I/SNRVE

24LC64T-E/SN

24LC08B/SN

24AA08/SN

24LC08B-E/SN

24LC08B-I/SNRVE

24LC08B-I/SNA27

24AA08-I/SN

24LC08BT/SNRVE

24AA08T/SN

24LC08BT-I/SNRVE

24LC08BT-I/SNA23

24LC08BT-I/SNA27

24AA08T-I/SN

24LC08BT-E/SN

24LC08B-I/SN

24LC08BT/SN

24LC08BT-I/SN

24LC16B/SN

24LC16B-E/SN

24LC16B-E/SNA26

24LC16B-I/SN

24AA16-I/SN

24AA16-I/SNB22

24LC16BT/SN

24LC16BT/SNA31

24LC16BT/SNRVE

24LC16BT-I/SN

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JAON-04TMOL584 - CCB 4539 Initial Notice: Qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper wire with gold flash (CuPdAu) bond wire material assembled at MMT assembly site.

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24LC16BT-I/SNRVE  
24AA16T-I/SN  
24LC16BT-E/SN  
24LC16BT-E/SNA26  
24AA01/SN  
24AA01-I/SN  
24AA01T/SN  
24AA01T-I/SN  
24LC02B/SN  
24AA02/SN  
24LC02B-E/SN  
24LC02B-I/SN  
24AA02-I/SN  
24LC02BT/SN  
24LC02BT/SNA31  
24AA02T/SN  
24LC02BT-I/SN  
24AA02T-I/SN  
24LC02BT-E/SN  
24LC04B/SN  
24AA04/SN  
24LC04B-E/SN  
24AA04-I/SN  
24LC04BT/SN  
24AA04T/SN  
24AA04T-I/SN  
24AA04T-I/SNB24  
24LC04BT-E/SN  
24LC32A/SN  
24LC32A-E/SN  
24LC32A-I/SN  
24LC32A-I/SNA27  
24LC32A-I/SNRVE  
24AA32A-I/SN  
24AA32A-I/SNRVE  
34A47F-I/SN  
24LC32AT/SN  
24LC32AT-I/SN  
24LC32AT-I/SNA23  
24LC32AT-I/SNA27  
24LC32AT-I/SNRVE  
24AA32AT-I/SN  
24AA32AT-I/SNRVE  
34A47FT-I/SN  
24LC32AT-E/SN  
PIC12F629-C/SN  
PIC12F629-E/SN244  
PIC12F629-E/SN  
PIC12F629-I/SN102



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JAON-04TMOL584 - CCB 4539 Initial Notice: Qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper wire with gold flash (CuPdAu) bond wire material assembled at MMT assembly site.

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PIC12F629-I/SN148

PIC12F629-I/SN206

PIC12F629-I/SN207

PIC12F629-I/SN208

PIC12F629-I/SN209

PIC12F629-I/SN

HA688-I/SN

PIC12F629-I/SNC24

PIC12F629T-C/SN

PIC12F629T-I/SN039

PIC12F629T-I/SN065

PIC12F629T-I/SN069

PIC12F629T-I/SN084

PIC12F629T-I/SN091

PIC12F629T-I/SN102

PIC12F629T-I/SN138

PIC12F629T-I/SN148

PIC12F629T-I/SN211

PIC12F629T-I/SN213

PIC12F629T-I/SN214

PIC12F629T-I/SN220

PIC12F629T-I/SN232

PIC12F629T-I/SN233

PIC12F629T-I/SN241

PIC12F629T-I/SN242

PIC12F629T-I/SN245

PIC12F629T-I/SN247

PIC12F629T-I/SN248

PIC12F629T-I/SN249

PIC12F629T-I/SN250

PIC12F629T-I/SN

PIC12F629T-I/SNC19

PIC12F629T-E/SN244

PIC12F629T-E/SN246

PIC12F629T-E/SN

25LC160B-E/SN

25LC160B-I/SN

25AA160B-I/SN

25LC160BT-I/SN

25AA160BT-I/SN

25LC160BT-E/SN

25LC080B-E/SN

25LC080B-I/SN

25AA080B-I/SN

25LC080BT-I/SN

25AA080BT-I/SN

25AA080BT-I/SNB21

25LC080BT-E/SN

25LC080A-E/SN

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JAON-04TMOL584 - CCB 4539 Initial Notice: Qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper wire with gold flash (CuPdAu) bond wire material assembled at MMT assembly site.

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25LC080A-I/SN

25AA080A-I/SN

25LC080A-H/SN

25LC080AT-H/SN

25LC080AT-I/SN

25AA080AT-I/SN

25LC080AT-E/SN

25LC160A-E/SN

25AA160A-I/SN103

25LC160A-I/SN

25AA160A-I/SN

25AA160AT-I/SN103

25LC160AT-I/SN

25LC160AT-I/SNA79

25AA160AT-I/SN

25LC160AT-E/SN

93LC46A/SN

93LC46AX/SN

93LC46A-E/SN

93LC46AX-E/SN

93LC46A-I/SN

93LC46AX-I/SN

93AA46A-I/SN

93AA46AX-I/SN

93AA46AE48-I/SN

93LC46AT/SN

93LC46AXT/SN

93LC46AT-I/SN

93LC46AXT-I/SN

93AA46AT-I/SN

93AA46AXT-I/SN

93AA46AE48T-I/SN

93LC46AT-E/SN

93LC46AXT-E/SN

93LC46B-E/SN

93LC46BX-E/SN

93AA46B-I/SN

93AA46BX-I/SN

93AA46BT-I/SN

93AA46BXT-I/SN

93LC46BT-E/SN

93LC46BXT-E/SN

93C46B/SN

93C46BX/SN

93C46B-E/SN

93C46BX-E/SN

93C46B-I/SN

93C46BX-I/SN

93C46BT/SN

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JAON-04TMOL584 - CCB 4539 Initial Notice: Qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper wire with gold flash (CuPdAu) bond wire material assembled at MMT assembly site.

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93C46BXT-I/SN

93C46BT-I/SN

93C46BXT-I/SN

93C46BT-E/SN

93C46BXT-E/SN

93C46A-E/SN

93C46AX-E/SN

93C46A-I/SN

93C46AX-I/SN

93C46AT-I/SN

93C46AXT-I/SN

93C46AT-E/SN

93C46AXT-E/SN

93LC46C-E/SN

93LC46CX-E/SN

93LC46C-I/SN

93LC46CX-I/SN

93AA46C-I/SN

93AA46CX-I/SN

93LC46CT-I/SN

93LC46CXT-I/SN

93AA46CT-I/SN

93AA46CXT-I/SN

93LC46CT-E/SN

93LC46CXT-E/SN

93LC56A/SN

93LC56B/SN

93LC56BX/SN

93LC56C-E/SN

93LC56CX-E/SN

93LC56A-E/SN

93LC56AX-E/SN

93LC56B-E/SN

93LC56BX-E/SN

93LC56C-I/SN

93LC56CX-I/SN

93AA56C-I/SN

93AA56CX-I/SN

93LC56A-I/SN

93LC56AX-I/SN

93AA56A-I/SN

93AA56AX-I/SN

93LC56B-I/SN

93LC56BX-I/SN

93AA56B-I/SN

93AA56BX-I/SN

93LC56AT/SN

93LC56BT/SN

93LC56BXT/SN

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JAON-04TMOL584 - CCB 4539 Initial Notice: Qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper wire with gold flash (CuPdAu) bond wire material assembled at MMT assembly site.

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93LC56CT-I/SN  
93LC56CXT-I/SN  
93AA56CT-I/SN  
93AA56CXT-I/SN  
93LC56AT-I/SN  
93LC56AXT-I/SN  
93AA56AT-I/SN  
93AA56AXT-I/SN  
93LC56BT-I/SN  
93LC56BXT-I/SN  
93AA56BT-I/SN  
93AA56BXT-I/SN  
93LC56CT-E/SN  
93LC56CXT-E/SN  
93LC56AT-E/SN  
93LC56AXT-E/SN  
93LC56BT-E/SN  
93LC56BXT-E/SN  
93LC66A/SN  
93LC66AX/SN  
93LC66B/SN  
93LC66BX/SN  
93LC66C-E/SN  
93LC66CX-E/SN  
93LC66A-E/SN  
93LC66AX-E/SN  
93LC66B-E/SN  
93LC66BX-E/SN  
93LC66C-I/SN  
93LC66CX-I/SN  
93AA66C-I/SN  
93AA66CX-I/SN  
93LC66A-I/SN  
93LC66AX-I/SN  
93AA66A-I/SN  
93AA66AX-I/SN  
93LC66B-I/SN  
93LC66B-I/SN15K  
93LC66BX-I/SN  
93AA66B-I/SN  
93AA66BX-I/SN  
93LC66AT/SN  
93LC66BT/SN  
93LC66CT-I/SN  
93LC66CXT-I/SN  
93AA66CT-I/SN  
93AA66CXT-I/SN  
93LC66AT-I/SN  
93LC66AXT-I/SN

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JAON-04TMOL584 - CCB 4539 Initial Notice: Qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper wire with gold flash (CuPdAu) bond wire material assembled at MMT assembly site.

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93AA66AT-I/SN

93AA66AXT-I/SN

93LC66BT-I/SN

93LC66BT-I/SN15K

93LC66BXT-I/SN

93AA66BT-I/SN

93AA66BXT-I/SN

93LC66CT-E/SN

93LC66CXT-E/SN

93LC66AT-E/SN

93LC66AXT-E/SN

93LC66BT-E/SN

93LC66BXT-E/SN

93C46C-E/SN

93C46C-I/SN

93C46CT-I/SN

93C46CT-E/SN

93C56C-E/SN

93C56A-E/SN

93C56B-E/SN

93C56C-I/SN

93C56A-I/SN

93C56B-I/SN

93C56CT-I/SN

93C56AT-I/SN

93C56BT-I/SN

93C56CT-E/SN

93C56AT-E/SN

93C56BT-E/SN

93C66C-E/SN

93C66A-E/SN

93C66B-E/SN

93C66C-I/SN

93C66A-I/SN

93C66CT-I/SN

93C66AT-I/SN

93C66CT-E/SN

93C66AT-E/SN

93C66BT-E/SN

MCP2122-E/SN

MCP2122T-E/SN

93LC76C-E/SN

93LC76C-I/SN

93AA76C-I/SN

93LC76CT-I/SN

93AA76CT-I/SN

93LC76CT-E/SN

93LC86C-E/SN

93LC86C-I/SN

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JAON-04TMOL584 - CCB 4539 Initial Notice: Qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper wire with gold flash (CuPdAu) bond wire material assembled at MMT assembly site.

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93AA86C-I/SN  
93LC86CT-I/SN  
93AA86CT-I/SN  
93LC86CT-E/SN  
93C76C-E/SN  
93C76C-I/SN  
93C76CT-I/SN  
93C76CT-E/SN  
93C86C-E/SN  
93C86C-I/SN  
93C86CT-I/SN  
93C86CT-E/SN  
93LC76A-E/SN  
93LC76B-E/SN  
93LC76A-I/SN  
93AA76A-I/SN  
93LC76B-I/SN  
93AA76B-I/SN  
93LC76AT-I/SN  
93AA76AT-I/SN  
93LC76BT-I/SN  
93AA76BT-I/SN  
93LC76AT-E/SN  
93LC76BT-E/SN  
93LC86A-E/SN  
93LC86B-E/SN  
93LC86A-I/SN  
93AA86A-I/SN  
93LC86B-I/SN  
93AA86B-I/SN  
93LC86AT-I/SN  
93AA86AT-I/SN  
93LC86BT-I/SN  
93AA86BT-I/SN  
93LC86AT-E/SN  
93LC86BT-E/SN  
93C76A-E/SN  
93C76B-E/SN  
93C76A-I/SN  
93C76B-I/SN  
93C76AT-I/SN  
93C76BT-I/SN  
93C76AT-E/SN  
93C76BT-E/SN  
93C86A-E/SN  
93C86B-E/SN  
93C86A-I/SN  
93C86B-I/SN  
93C86AT-I/SN

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JAON-04TMOL584 - CCB 4539 Initial Notice: Qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper wire with gold flash (CuPdAu) bond wire material assembled at MMT assembly site.

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93C86BT-I/SN

93C86AT-E/SN

93C86BT-E/SN

MCP4021-202E/SN

MCP4021-502E/SN

MCP4021-103E/SN

MCP4021-503E/SN

MCP4021T-202E/SN

MCP4021T-502E/SN

MCP4021T-103E/SN

MCP4021T-503E/SN

MCP4011-202E/SN

MCP4011-502E/SN

MCP4011-103E/SN

MCP4011-503E/SN

MCP4011T-202E/SN

MCP4011T-502E/SN

MCP4011T-103E/SN

MCP4011T-503E/SN

25LC256-E/SN

25AA256-E/SN

25LC256-I/SN

25LC256-I/SNRVB

25AA256-I/SN

25LC256-H/SN

25LC256T-H/SN

25LC256T-I/SN

25LC256T-I/SNRVB

25AA256T-I/SN

25AA256T-I/SNB31

25LC256T-E/SN

25AA256T-E/SN

25LC320A-E/SN

25LC320A-I/SN

25AA320A-I/SN

25AA320A-I/SNB22

25LC320A-H/SN

25LC320AT-H/SN

25LC320AT-I/SN

25AA320AT-I/SN

25AA320AT-I/SNB22

25LC320AT-E/SN

25LC160D-E/SN

25AA160D-E/SN

25LC160D-I/SN

25AA160D-I/SN

25LC160D-H/SN

25LC160DT-H/SN

25LC160DT-I/SN

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JAON-04TMOL584 - CCB 4539 Initial Notice: Qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper wire with gold flash (CuPdAu) bond wire material assembled at MMT assembly site.

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25AA160DT-I/SN

25LC160DT-E/SN

25LC160DT-E/SN16KA21

25AA160DT-E/SN

25LC080D-E/SN

25LC080D-I/SN

25AA080D-I/SN

25LC080D-H/SN

25LC080DT-H/SN

25LC080DT-I/SN

25AA080DT-I/SN

25AA080DT-I/SN-SCI

25LC080DT-E/SN

25LC160C-E/SN

25LC160C-I/SN

25AA160C-I/SN

25LC160C-H/SN

25LC160CT-H/SN

25LC160CT-I/SN

25AA160CT-I/SN

25LC160CT-E/SN

25LC080C-E/SN

25LC080C-I/SN

25AA080C-I/SN

25LC080C-H/SN

25LC080CT-H/SN

25LC080CT-I/SN

25AA080CT-I/SN

25LC080CT-E/SN

MCP4131-502E/SN

MCP4131-103E/SN

MCP4131-104E/SN

MCP4131-503E/SN

MCP4141-502E/SN

MCP4141-103E/SN

MCP4141-104E/SN

MCP4141-503E/SN

MCP4151-502E/SN

MCP4151-103E/SN

MCP4151-104E/SN

MCP4151-503E/SN

MCP4161-502E/SN

MCP4161-103E/SN

MCP4161-104E/SN

MCP4161-503E/SN

MCP4132-502E/SN

MCP4132-103E/SN

MCP4132-104E/SN

MCP4132-503E/SN



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JAON-04TMOL584 - CCB 4539 Initial Notice: Qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper wire with gold flash (CuPdAu) bond wire material assembled at MMT assembly site.

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MCP4142-502E/SN  
MCP4142-103E/SN  
MCP4142-104E/SN  
MCP4142-503E/SN  
MCP4152-502E/SN  
MCP4152-103E/SN  
MCP4152-104E/SN  
MCP4152-503E/SN  
MCP4162-502E/SN  
MCP4162-103E/SN  
MCP4162-104E/SN  
MCP4162-503E/SN  
MCP4131T-502E/SN  
MCP4131T-103E/SN  
MCP4131T-104E/SN  
MCP4131T-503E/SN  
MCP4141T-502E/SN  
MCP4141T-103E/SN  
MCP4141T-104E/SN  
MCP4141T-503E/SN  
MCP4151T-502E/SN  
MCP4151T-103E/SN  
MCP4151T-104E/SN  
MCP4151T-503E/SN  
MCP4161T-502E/SN  
MCP4161T-103E/SN  
MCP4161T-104E/SN  
MCP4161T-503E/SN  
MCP4132T-502E/SN  
MCP4132T-103E/SN  
MCP4132T-104E/SN  
MCP4132T-503E/SN  
MCP4142T-502E/SN  
MCP4142T-103E/SN  
MCP4142T-104E/SN  
MCP4142T-503E/SN  
MCP4152T-502E/SN  
MCP4152T-103E/SN  
MCP4152T-104E/SN  
MCP4152T-503E/SN  
MCP4162T-502E/SN  
MCP4162T-103E/SN  
MCP4162T-104E/SN  
MCP4162T-503E/SN  
25LC128-E/SN  
25AA128-E/SN  
25LC128-I/SN  
25AA128-I/SN  
25LC128-H/SN

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JAON-04TMOL584 - CCB 4539 Initial Notice: Qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper wire with gold flash (CuPdAu) bond wire material assembled at MMT assembly site.

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25LC128T-H/SN

25LC128T-I/SN

25AA128T-I/SN

25AA128T-I/SNRVA

25LC128T-E/SN

25LC128T-E/SNRVA

25AA128T-E/SN

25LC640A-E/SN

25AA640A-E/SN

25LC640A-M/SN

25LC640A-I/SN

25AA640A-I/SN

25LC640A-H/SN

25LC640AT-H/SN

25LC640AT-I/SN

25AA640AT-I/SN

25AA640AT-I/SNB23

25LC640AT-M/SN

25LC640AT-E/SN

25AA640AT-E/SN

PIC12F683-E/SN084

PIC12F683-E/SN

PIC12F683-I/SN075

PIC12F683-I/SN

PIC12F683T-I/SN072

PIC12F683T-I/SN091

PIC12F683T-I/SN

PIC12F683T-E/SN084

PIC12F683T-E/SN092

PIC12F683T-E/SN098

PIC12F683T-E/SN

PIC12F635-E/SN

PIC12F635-I/SN057

PIC12F635-I/SN

PIC12F635T-I/SN050

PIC12F635T-I/SN058

PIC12F635T-I/SN

PIC12F510-E/SN

PIC12F510-I/SN

PIC12F510-I/SNC06

MCV08A-I/SN

PIC12F510T-I/SN026

PIC12F510T-I/SN041

PIC12F510T-I/SN058

PIC12F510T-I/SN064

PIC12F510T-I/SN065

PIC12F510T-I/SN073

PIC12F510T-I/SN074

PIC12F510T-I/SN075

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JAON-04TMOL584 - CCB 4539 Initial Notice: Qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper wire with gold flash (CuPdAu) bond wire material assembled at MMT assembly site.

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PIC12F510T-I/SN077  
PIC12F510T-I/SN078  
PIC12F510T-I/SN079  
PIC12F510T-I/SN  
PIC12F510T-E/SN070  
PIC12F510T-E/SN  
PIC12F519-E/SN  
PIC12F519-I/SN039  
PIC12F519-I/SN041  
PIC12F519-I/SN  
PIC12F519T-I/SN025  
PIC12F519T-I/SN029  
PIC12F519T-I/SN030  
PIC12F519T-I/SN031  
PIC12F519T-I/SN033  
PIC12F519T-I/SN035  
PIC12F519T-I/SN037  
PIC12F519T-I/SN039  
PIC12F519T-I/SN040  
PIC12F519T-I/SN041  
PIC12F519T-I/SN042  
PIC12F519T-I/SN044  
PIC12F519T-I/SN047  
PIC12F519T-I/SN048  
PIC12F519T-I/SN  
PIC12F519T-E/SN  
PIC12F617-E/SN020  
PIC12F617-E/SN031  
PIC12F617-E/SN033  
PIC12F617-E/SN034  
PIC12F617-E/SN  
PIC12F617-I/SN030  
PIC12F617-I/SN032  
PIC12F617-I/SN053  
PIC12F617-I/SN  
PIC12F617-I/SNC15  
PIC12F617T-I/SN022  
PIC12F617T-I/SN028  
PIC12F617T-I/SN030  
PIC12F617T-I/SN032  
PIC12F617T-I/SN038  
PIC12F617T-I/SN044  
PIC12F617T-I/SN053  
PIC12F617T-I/SN059  
PIC12F617T-I/SN  
PIC12F617T-I/SNC15  
PIC12F617T-E/SN020  
PIC12F617T-E/SN024  
PIC12F617T-E/SN026

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JAON-04TMOL584 - CCB 4539 Initial Notice: Qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper wire with gold flash (CuPdAu) bond wire material assembled at MMT assembly site.

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PIC12F617T-E/SN027  
PIC12F617T-E/SN031  
PIC12F617T-E/SN033  
PIC12F617T-E/SN034  
PIC12F617T-E/SN036  
PIC12F617T-E/SN037  
PIC12F617T-E/SN050  
PIC12F617T-E/SN051  
PIC12F617T-E/SN052  
PIC12F617T-E/SN055  
PIC12F617T-E/SN067  
PIC12F617T-E/SN071  
PIC12F617T-E/SN  
TCN75AVOA  
MCP9801-M/SN  
MCP9801-M/SNRC2  
MCP9801T-M/SN  
MCP9801T-M/SNRC2  
TCN75AVOA713  
MCP9803-M/SN  
MCP9803-M/SNRC2  
MCP9803T-M/SN  
MCP9803T-M/SNRC2  
MCP3550-50E/SN  
MCP3550-60E/SN  
MCP3550T-50E/SN  
MCP3550T-60E/SN  
MCP3551-E/SN  
MCP3551T-E/SN  
MCP3553-E/SN  
MCP3553T-E/SN  
MCP4822-E/SN  
MCP4802-E/SN  
MCP4812-E/SN  
MCP4822T-E/SN  
MCP4802T-E/SN  
MCP4812T-E/SN  
PIC12F508-E/SN  
PIC12F508-I/SN038  
PIC12F508-I/SN080  
PIC12F508-I/SN  
HA1100/SN  
PIC12F508T-I/SN020  
PIC12F508T-I/SN025  
PIC12F508T-I/SN040  
PIC12F508T-I/SN045  
PIC12F508T-I/SN056  
PIC12F508T-I/SN066  
PIC12F508T-I/SN080

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JAON-04TMOL584 - CCB 4539 Initial Notice: Qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper wire with gold flash (CuPdAu) bond wire material assembled at MMT assembly site.

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PIC12F508T-I/SN

PIC12F508T-E/SN079

PIC12F508T-E/SN

PIC12F509-E/SN055

PIC12F509-E/SN

PIC12F509-I/SN051

PIC12F509-I/SN

PIC12F509T-I/SN047

PIC12F509T-I/SN048

PIC12F509T-I/SN051

PIC12F509T-I/SN058

PIC12F509T-I/SN

PIC12F509T-E/SN052

PIC12F509T-E/SN055

PIC12F509T-E/SN

25LC010A-E/SN

25LC010A-I/SN

25AA010A-I/SN

25LC010A-H/SN

25LC010AT-H/SN

25LC010AT-I/SN

25AA010AT-I/SN

25LC010AT-E/SN

25LC020A-E/SN

25LC020A-I/SN

25AA020A-I/SN

25AA02E48-I/SN

25AA02E64-I/SN

25AA02UID-I/SN

25LC020A-H/SN

25LC020AT-H/SN

25LC020AT-I/SN

25AA020AT-I/SN

25AA02E48T-I/SN

25AA02E64T-I/SN

25AA02UIDT-I/SN

25LC020AT-E/SN

25LC040A-E/SN

25LC040A-M/SN

25LC040A-I/SN103

25LC040A-I/SN

25AA040A-I/SN

25LC040A-H/SN

25LC040AT-H/SN

25LC040AT-I/SN103

25LC040AT-I/SN

25AA040AT-I/SN

25LC040AT-M/SN

25LC040AT-E/SN

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JAON-04TMOL584 - CCB 4539 Initial Notice: Qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper wire with gold flash (CuPdAu) bond wire material assembled at MMT assembly site.

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PIC12F615-E/SN

PIC12F615-I/SN083

PIC12F615-I/SN

PIC12F615-H/SN

PIC12F615T-I/SN020

PIC12F615T-I/SN043

PIC12F615T-I/SN051

PIC12F615T-I/SN057

PIC12F615T-I/SN058

PIC12F615T-I/SN071

PIC12F615T-I/SN076

PIC12F615T-I/SN079

PIC12F615T-I/SN083

PIC12F615T-I/SN

PIC12F615T-E/SN

PIC12HV615-E/SN

PIC12HV615-I/SN

PIC12HV615T-I/SN022

PIC12HV615T-I/SN

PIC12HV615T-E/SN035

PIC12HV615T-E/SN043

PIC12HV615T-E/SN044

PIC12HV615T-E/SN

PIC12F609-E/SN

PIC12F609-I/SN

PIC12F609T-I/SN027

PIC12F609T-I/SN

PIC12F609T-E/SN

PIC12HV609-E/SN

PIC12HV609-I/SN

PIC12HV609T-I/SN

25LC512-E/SN

25LC512-M/SN

25LC512-I/SN

25LC512T-I/SN

25LC512T-M/SN

25LC512T-E/SN

25AA512-I/SN

25AA512T-I/SN

25AA512T-I/SN-SCI

MCP3422A0-E/SN

MCP3426A0-E/SN

MCP3422A0T-E/SN

MCP3426A0T-E/SN

MCP3422A1-E/SN

MCP3426A1-E/SN

MCP3422A1T-E/SN

MCP3426A1T-E/SN

MCP3422A2-E/SN

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JAON-04TMOL584 - CCB 4539 Initial Notice: Qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper wire with gold flash (CuPdAu) bond wire material assembled at MMT assembly site.

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MCP3426A2-E/SN

MCP3422A2T-E/SN

MCP3426A2T-E/SN

MCP3422A3-E/SN

MCP3426A3-E/SN

MCP3422A3T-E/SN

MCP3426A3T-E/SN

MCP3422A4-E/SN

MCP3426A4-E/SN

MCP3422A4T-E/SN

MCP3426A4T-E/SN

MCP3422A5-E/SN

MCP3426A5-E/SN

MCP3422A5T-E/SN

MCP3426A5T-E/SN

MCP3422A6-E/SN

MCP3426A6-E/SN

MCP3422A6T-E/SN

MCP3426A6T-E/SN

MCP3422A7-E/SN

MCP3426A7-E/SN

MCP3422A7T-E/SN

MCP3426A7T-E/SN

24LC08BH-E/SN

24LC08BH-I/SN

24AA08H-I/SN

24LC08BHT-I/SN

24AA08HT-I/SN

24LC08BHT-E/SN

24AA16-E/SN

24LC16B-M/SN

24LC16BT/SNA79

24AA16T-I/SNB22

24LC16BT-M/SN

24AA16T-E/SN

24LC16BH-E/SN

24LC16BH-I/SN

24AA16H-I/SN

24LC16BHT-I/SN

24AA16HT-I/SN

24LC16BHT-E/SN

24AA32AT-I/SNB79

24LC32AF-E/SN

24LC32AF-I/SN

24AA32AF-I/SN

24LC32AFT-I/SN

24AA32AFT-I/SN

24LC32AFT-E/SN

24AA64-E/SN

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JAON-04TMOL584 - CCB 4539 Initial Notice: Qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper wire with gold flash (CuPdAu) bond wire material assembled at MMT assembly site.

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~~24LC64-I/SN100~~

24AA64-I/SN101

24FC64-I/SN

24LC64T-I/SN100

24AA64T-I/SN101

24LC64T-I/SNA79

24AA64T-I/SNB79

24FC64T-I/SN

24LC64T-E/SNA31

24AA64T-E/SN

24LC64F-E/SN

24LC64F-I/SN

24AA64F-I/SN

24FC64F-I/SN

24LC64FT-I/SN

24AA64FT-I/SN

24FC64FT-I/SN

24LC64FT-E/SN

24FC128-E/SN

24LC128-I/SNRVF

24LC128T-I/SNRVF

24AA128T-I/SNRVF

24FC128T-E/SN

24LC04BT-I/SNA79

24LC04BH-E/SN

24LC04BH-I/SN

24AA04H-I/SN

24LC04BHT-I/SN

24AA04HT-I/SN

24LC04BHT-E/SN

24LC512-E/SN

24LC512-I/SN

24AA512-I/SN

24FC512-I/SN

24FC512-I/SNC79

24FC512T-I/SN101

24LC512T-I/SN

24AA512T-I/SN

24FC512T-I/SN

24FC512T-I/SNC21

24FC512T-I/SNC79

24LC512T-E/SN

24AA256-E/SN

24FC256-E/SN

24AA256-I/SN104

24AA256T-I/SN104

24AA256T-I/SN105

24LC256T-I/SNRVF

24AA256T-E/SN



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JAON-04TMOL584 - CCB 4539 Initial Notice: Qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper wire with gold flash (CuPdAu) bond wire material assembled at MMT assembly site.

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Z4FC2561-E/SN

24AA256UID-I/SN

24AA256UIDT-I/SN

MCP6N11-001E/SN

MCP6N11T-001E/SN

MCP6N11-002E/SN

MCP6N11T-002E/SN

MCP6N11-005E/SN

MCP6N11T-005E/SN

MCP6N11-010E/SN

MCP6N11T-010E/SN

MCP6N11-100E/SN

MCP6N11T-100E/SN

MCP4801-E/SN

MCP4811-E/SN

MCP4821-E/SN

MCP4901-E/SN

MCP4911-E/SN

MCP4921-E/SN

MCP4801T-E/SN

MCP4811T-E/SN

MCP4821T-E/SN

MCP4901T-E/SN

MCP4911T-E/SN

MCP4921T-E/SN

PIC12F752-E/SN

PIC12F752-I/SN

PIC12F752T-I/SN024

PIC12F752T-I/SN

PIC12HV752-E/SN

PIC12HV752-I/SN

MCP6482-E/SN

MCP6492-E/SN

MCP6472-E/SN

MCP6482T-E/SN

MCP6492T-E/SN

MCP6472T-E/SN

MCP6422-E/SN

MCP6422T-E/SN

34AA04-E/SN

34AA04-I/SN

34AA04T-I/SN

34AA04T-E/SN

24AA044-E/SN

24AA044-I/SN

24AA044T-I/SN

24AA044T-E/SN

11LC010-E/SN

11LC010-I/SN

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JAON-04TMOL584 - CCB 4539 Initial Notice: Qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper wire with gold flash (CuPdAu) bond wire material assembled at MMT assembly site.

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11AA010-I/SN

11LC010T-I/SN

11AA010T-I/SN

11LC010T-E/SN

11LC020-E/SN

11LC020-I/SN

11AA020-I/SN

11AA02E48-I/SN

11AA02E64-I/SN

11AA02UID-I/SN

11LC020T-I/SN

11AA020T-I/SN

11AA02E48T-I/SN

11AA02E64T-I/SN

11AA02UIDT-I/SN

11LC020T-E/SN

11LC040-E/SN

11LC040-I/SN

11AA040-I/SN

11LC040T-I/SN

11AA040T-I/SN

11LC040T-E/SN

11LC080-E/SN

11LC080-I/SN

11AA080-I/SN

11LC080T-I/SN

11AA080T-I/SN

11LC080T-E/SN

11LC160-E/SN

11LC160-I/SN

11AA160-I/SN

11LC160T-I/SN

11AA160T-I/SN

11LC160T-E/SN

11LC161-E/SN

11LC161-I/SN

11AA161-I/SN

11LC161T-I/SN

11AA161T-I/SN

11LC161T-E/SN

24AA02/SNB79

24LC02B-I/SNA32

24LC02BT-I/SN104

24LC02BT-I/SNA32

24LC01BH-E/SN

24LC01BH-I/SN

24AA01H-I/SN

24LC01BHT-I/SN

24AA01HT-I/SN

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JAON-04TMOL584 - CCB 4539 Initial Notice: Qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper wire with gold flash (CuPdAu) bond wire material assembled at MMT assembly site.

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~~24LC02BHT-E/SN~~

24LC02BH-E/SN

24AA02E48-E/SN

24AA02E64-E/SN

24LC02BH-I/SN100

24LC02BH-I/SN

24AA02H-I/SN

24AA02E48-I/SN

24AA02E64-I/SN

24AA02UID-I/SN

24LC02BHT-I/SN

24AA02HT-I/SN

24AA02E48T-I/SN

24AA02E64T-I/SN

24AA02UIDT-I/SN

24LC02BHT-E/SN

24AA02E48T-E/SN

24AA02E64T-E/SN

24LCS52/SN

24LCS52-I/SN

24AA52-I/SN

24LCS52T/SN

24LCS52T-I/SN

24AA52T-I/SN

24LC024/SN

24LC025/SN

24VL024/SN

24VL025/SN

24LC024-E/SN

24LC025-E/SN

24LC024-I/SN

24AA024-I/SN

24LC025-I/SN

24AA025-I/SN

24LC024T/SN

24LC025T/SN

24VL024T/SN

24VL025T/SN

24LC024T-I/SN

24AA024T-I/SN

24LC025T-I/SN

24AA025T-I/SN

24LC024T-E/SN

24LC025T-E/SN

24VL014/SN

24LC014-E/SN

24LC014-I/SN

24AA014-I/SN

24VL014T/SN

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JAON-04TMOL584 - CCB 4539 Initial Notice: Qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper wire with gold flash (CuPdAu) bond wire material assembled at MMT assembly site.

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24LC014T-I/SN

24AA014T-I/SN

24LC014T-E/SN

24C01C/SN

24C01C-E/SN

24C01C-I/SN

24C01CT/SN

24C01CT-I/SN

24C01CT-E/SN

24VL014H/SN

24LC014H-E/SN

24LC014H-I/SN

24AA014H-I/SN

24VL014HT/SN

24LC014HT-I/SN

24AA014HT-I/SN

24LC014HT-E/SN

24VL024H/SN

24LC024H-E/SN

24AA025E48-E/SN

24AA025E64-E/SN

24LC024H-I/SN

24AA024H-I/SN

24AA025E48-I/SN

24AA025E64-I/SN

24AA025UID-I/SN

24VL024HT/SN

24LC024HT-I/SN

24AA024HT-I/SN

24AA025E48T-I/SN

24AA025E64T-I/SN

24AA025UIDT-I/SN

24LC024HT-E/SN

24AA025E48T-E/SN

24AA025E64T-E/SN

34VL02/SN

34LC02-E/SN

34AA02-E/SN

34LC02-I/SN

34AA02-I/SN

34VL02T/SN

34LC02T-I/SN

34AA02T-I/SN

34LC02T-E/SN

34AA02T-E/SN

MCP79410-I/SN

MCP79411-I/SN

MCP79412-I/SN

MCP79410T-I/SN

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JAON-04TMOL584 - CCB 4539 Initial Notice: Qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper wire with gold flash (CuPdAu) bond wire material assembled at MMT assembly site.

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MCP794111-I/SN

MCP79412T-I/SN

MCP79400-I/SN

MCP79401-I/SN

MCP79402-I/SN

MCP79400T-I/SN

MCP79401T-I/SN

MCP79402T-I/SN

MCP7940N-E/SN

MCP7940N-I/SN

MCP7940M-I/SN

MCP7940NT-I/SN

MCP7940MT-I/SN

MCP7940NT-E/SN

PIC12LF1552-E/SN

PIC12LF1552-I/SN

PIC12LF1552T-I/SN021

PIC12LF1552T-I/SN023

PIC12LF1552T-I/SN

25K512-I/SN

25A512-I/SN

25K512T-I/SN

25A512T-I/SN

PIC12F1822-E/SN

PIC12F1822-E/SNC07

PIC12F1822-I/SN052

PIC12F1822-I/SN

PIC12F1822-I/SNC08

PIC12F1822-I/SNC11

PIC12F1822-I/SNC15

PIC12F1822T-I/SN039

PIC12F1822T-I/SN049

PIC12F1822T-I/SN052

PIC12F1822T-I/SN053

PIC12F1822T-I/SN

PIC12F1822T-I/SNC08

PIC12F1822T-I/SNC15

PIC12F1822T-E/SN046

PIC12F1822T-E/SN

PIC12F1822T-E/SNC07

PIC12LF1822-E/SN

PIC12LF1822-I/SN

PIC12LF1822T-I/SN

PIC12LF1822T-E/SN

PIC12F1840-E/SN

PIC12F1840-I/SN

PIC12F1840T-I/SN

PIC12F1840T-E/SN

PIC12LF1840-E/SN

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JAON-04TMOL584 - CCB 4539 Initial Notice: Qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper wire with gold flash (CuPdAu) bond wire material assembled at MMT assembly site.

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MTCH112-I/SN

PIC12LF1840-I/SN

MTCH112T-I/SN

PIC12LF1840T-I/SN

PIC12LF1840T-E/SN

PIC12F1501-E/SN047

PIC12F1501-E/SN048

PIC12F1501-E/SN

PIC12F1501-I/SN

PIC12F1501-I/SNH3A

PIC12F1501T-I/SN027

PIC12F1501T-I/SN

PIC12F1501T-I/SNH1A

PIC12F1501T-I/SNH2A

PIC12F1501T-I/SNH3A

PIC12F1501T-I/SNL1A

PIC12F1501T-I/SNL2A

PIC12F1501T-I/SNL3A

PIC12F1501T-I/SNL4A

PIC12F1501T-E/SN022

PIC12F1501T-E/SN032

PIC12F1501T-E/SN033

PIC12F1501T-E/SN034

PIC12F1501T-E/SN035

PIC12F1501T-E/SN047

PIC12F1501T-E/SN048

PIC12F1501T-E/SN052

PIC12F1501T-E/SN

PIC12LF1501-E/SN

PIC12LF1501-I/SN

PIC12LF1501T-I/SN023

PIC12LF1501T-I/SN024

PIC12LF1501T-I/SN

PIC12LF1501T-E/SN

PIC12F1612-E/SN

PIC12F1612-I/SN

PIC12LF1612-E/SN

PIC12LF1612-I/SN

PIC12LF1612T-I/SN

PIC12F1571-E/SN

PIC12F1572-E/SN

PIC12F1571-I/SN030

PIC12F1571-I/SN032

PIC12F1571-I/SN035

PIC12F1571-I/SN038

PIC12F1571-I/SN057

PIC12F1571-I/SN063

PIC12F1571-I/SN

PIC12F1572-I/SN

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JAON-04TMOL584 - CCB 4539 Initial Notice: Qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper wire with gold flash (CuPdAu) bond wire material assembled at MMT assembly site.

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PIC12F1572T-I/SN020  
PIC12F1571T-I/SN030  
PIC12F1572T-I/SN034  
PIC12F1571T-I/SN038  
PIC12F1571T-I/SN042  
PIC12F1572T-I/SN048  
PIC12F1572T-I/SN052  
PIC12F1571T-I/SN056  
PIC12F1571T-I/SN057  
PIC12F1571T-I/SN063  
PIC12F1572T-I/SN064  
PIC12F1571T-I/SN  
PIC12F1572T-I/SN  
PIC12F1572T-E/SN048  
PIC12F1571T-E/SN  
PIC12F1572T-E/SN  
PIC12LF1571-E/SN  
PIC12LF1572-E/SN  
PIC12LF1572-I/SN033  
PIC12LF1571-I/SN  
PIC12LF1572-I/SN  
PIC12LF1571T-I/SN026  
PIC12LF1571T-I/SN028  
PIC12LF1571T-I/SN029  
PIC12LF1571T-I/SN031  
PIC12LF1572T-I/SN033  
PIC12LF1571T-I/SN  
PIC12LF1572T-I/SN  
PIC12LF1572T-E/SN  
MCP2551-E/SN  
MCP2551-I/SN  
MCP2551T-I/SN  
MCP2551T-E/SN  
MCP2003-E/SN  
MCP2003T-E/SN  
MCP2004-E/SN  
MCP2004T-E/SN  
MCP2003A-E/SN  
MCP2003AT-E/SN  
MCP2004A-E/SN  
MCP2004AT-E/SN  
MCP2025-500E/SN  
MCP2025T-500E/SN  
MCP2025-330E/SN  
MCP2025T-330E/SN  
RE46C100S8F  
RE46C101S8F  
RE46C101S8TF  
RE46C100S8TF

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JAON-04TMOL584 - CCB 4539 Initial Notice: Qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper wire with gold flash (CuPdAu) bond wire material assembled at MMT assembly site.

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RE46C108S8F

RE46C108S8TF

RE46C317S8F

RE46C317S8TF

RE46C318S8F

RE46C318S8TF

TC1044SCOA

TC7660SCOA

TC7662BCOA

TC7660SVOA

TC1044SEOA

TC7660SEOA

TC7662BEOA

TC1044SEOA713

TC7660SEOA713

TC7660SEOA713BAA

TC7660SEOA713BAB

TC7662BEOA713

TC1044SCOA713

TC7660SCOA713

TC7662BCOA713

TC7660SVOA713

TC7660SEOA723

TC7660COA

TC7660EOA

TC7660MEOA

TC7660EOA713

TC7660MEOA713

TC7660COA713

TC7660EOA723

TC622COA

TC622VOA

TC622EOA

TC622EOA713

TC622COA713

TC622VOA713



**CCB 4539**  
**Pre and Post Change Summary**  
**PCN # JAON-04TMOL584**



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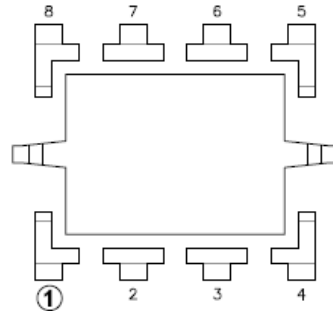
A Leading Provider of Smart, Connected and Secure Embedded Control Solutions



SMART | CONNECTED | SECURE

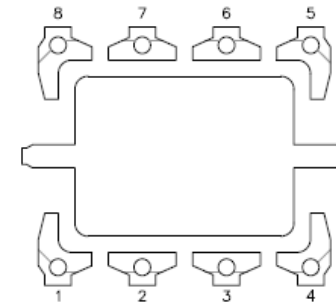
# Lead frame Comparison

## Pre Change

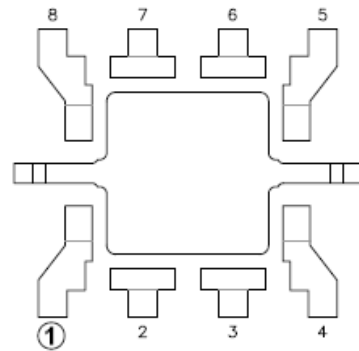


LF STRIP DENSITY: x140  
LF PAD SIZE: 95x130 mils  
LEAD LOCK: NO

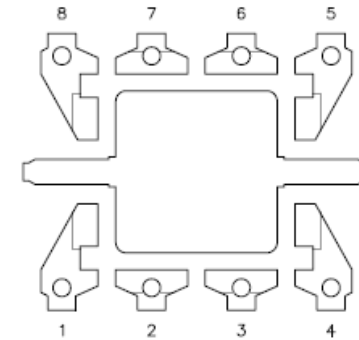
## Post Change



LF STRIP DENSITY: x320  
LF PAD SIZE: 95x130 mils  
LEAD LOCK: YES



LF STRIP DENSITY: x140  
LF PAD SIZE: 90x90 mils  
LEAD LOCK: NO



LF STRIP DENSITY: x320  
LF PAD SIZE: 90x90 mils  
LEAD LOCK: YES



**MICROCHIP**

## **QUALIFICATION PLAN SUMMARY**

**PCN #: JAON-04TMOL584**

**Date:  
January 21, 2021**

**Qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper with gold flash (CuPdAu) bond wire material assembled at MMT assembly site.**

**Purpose:** Qualification of a new lead frame design for selected products available in 8L SOIC package using 8390A die attach and palladium coated copper with gold flash (CuPdAu) bond wire material assembled at MMT assembly site.

**CCB No.:** 4539

<b><u>Misc.</u></b>	Assembly site	MMT
	BD Number	BDM-002810/A
	MP Code (MPC)	DE0244C2XB04
	Part Number (CPN)	PIC12F683-E/SN
	MSL information	MSL-1/260C
	Assembly Shipping Media (T/R, Tube/Tray)	Tube
	Base Quantity Multiple (BQM)	100
	Reliability Site	MTAI
<b><u>Lead-Frame</u></b>	Paddle size	95x130 mils
	Material	CDA194
	DAP Surface Prep	Bare Cu
	Treatment	BOT
	Process	Etched
	Lead-lock	Yes
	Part Number	10100842
	Lead Plating	Matte Tin
	Strip Size	239.0x70.0mm
	Strip Density	320 pads/strip
<b><u>Bond Wire</u></b>	Material	CuPdAu
<b><u>Die Attach</u></b>	Part Number	8390A
	Conductive	Yes
<b><u>MC</u></b>	Part Number	G600V
<b><u>PKG</u></b>	PKG Type	SOIC
	Pin/Ball Count	8
	PKG width/size	150 mils

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	Test Site	Special Instructions
<b>Standard Pb-free Solderability</b>	J-STD-002 ; Perform 8 hour steam aging for Matte tin finish and 1 hour steam aging for NiPdAu finish prior to testing.  Standard Pb-free: Matte tin/ NiPdAu finish, SAC solder, wetting temp 245°C for both SMD & through hole packages.	22	5	1	27	> 95% lead coverage	5		Standard Pb-free solderability is the requirement. SnPb solderability (backward solderability- SMD reflow soldering) is required for any plating related changes and highly recommended for other package BOM changes.
<b>Wire Bond Pull - WBP</b>	Mil. Std. 883-2011	5	0	3	15	0 fails after TC	5	MMT/MTAI	30 bonds from a minimum of 5 devices.
<b>Wire Bond Shear - WBS</b>	CDF-AEC-Q100-001	5	0	3	15		5	MMT/MTAI	30 bonds from a minimum of 5 devices.
<b>Wire Sweep</b>		5	0	3	15	0		MMT	Required for any reduction in wire bond thickness.
<b>Physical Dimensions</b>	Measure per JESD22 B100 and B108	10	0	3	30	0	5	MMT	
<b>External Visual</b>	Mil. Std. 883-2009/2010	All devices prior to submission for qualification testing	0	3	ALL	0	5	MMT/ MTAI	
<b>Preconditioning - Required for surface mount devices</b>	+150°C Bake for 24 hours, moisture loading requirements per MSL level + 3X reflow at peak reflow temperature per <b>Jedec-STD-020E</b> for package type; Electrical test pre and post stress at +25°C. <b>MSL1/260C</b>	231	15	3	738	0	15	MTAI	Spares should be properly identified. 77 parts from each lot to be used for HAST, Autoclave, Temp Cycle test.

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	Test Site	Special Instructions
<b>HAST</b>	+130°C/85% RH for 96 hours. Electrical test pre and post stress at +25°C and hot temp. Extend to 192 hrs post test at 25C	77	5	3	246	0	10	MTAI	Spares should be properly identified. Use the parts which have gone through
<b>Unbiased HAST</b>	+130°C/85% RH for 96 hrs. Electrical test pre and post stress at +25°C. Extend to 192 hrs post test at 25C	77	5	3	246	0	10	MTAI	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
<b>Temp Cycle</b>	-65°C to +150°C for 500 cycles. Electrical test pre and post stress at hot temp; 3 gram force WBP, on 5 devices from 1 lot, test following Temp Cycle stress. Extend to 1000 cycle post test at 25C	77	5	3	246	0	15	MTAI	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.